

### Surge Ratings

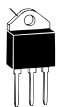
Series	I <sub>PP</sub>			I <sub>TSM</sub> / 60 Hz	di/dt
	1.2/50 <sup>1</sup> 8/20 <sup>2</sup>	10/350 <sup>1</sup> 1.2/50 <sup>2</sup>	10/1000 <sup>1</sup> 10/1000 <sup>2</sup>		
	A min	A min	A min		
E	5000 <sup>3</sup>	1500	1100	400	630

**Notes:**

1. Voltage waveform in  $\mu\text{s}$
2. Current waveform in  $\mu\text{s}$
3. For surge rating of P3800MEL, it is minimum 4kA and typical 5kA @8/20 $\mu\text{s}$ .

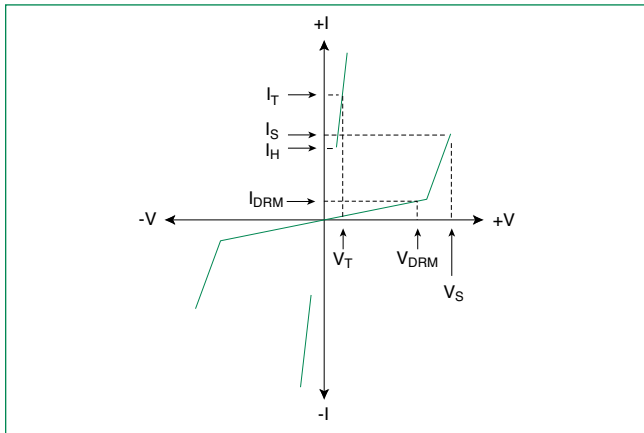
- Peak pulse current rating ( $I_{PP}$ ) is repetitive and guaranteed for the life of the product.  
 - The component must initially be in thermal equilibrium with  $-40^\circ\text{C} \leq T_J \leq +150^\circ\text{C}$

### Thermal Conditions

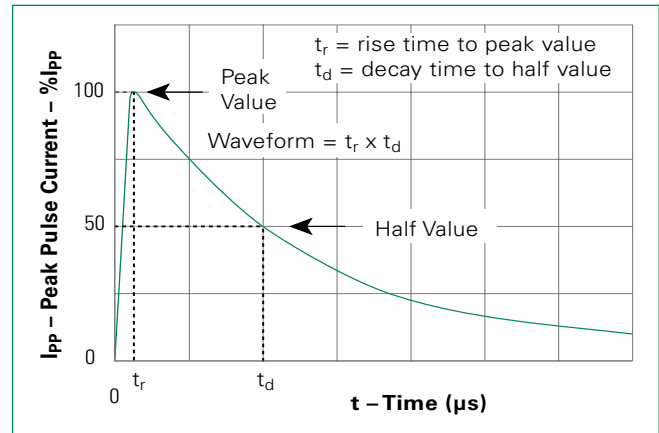
Package	Symbol	Parameter	Value	Unit
 TO-218	T <sub>JO</sub>	Operating Junction Temperature Range	-40 to +150	°C
	T <sub>S</sub>	Storage Temperature Range	-65 to +150	°C
	T <sub>C</sub>	Maximum Case Temperature	100	°C
	R <sub>θJC</sub> *	Thermal Resistance: Junction to Case	1.7	°C/W
	R <sub>θJA</sub>	Thermal Resistance: Junction to Ambient	56	°C/W

\*R<sub>θJC</sub> rating assumes the use of a heat sink and on state mode for extended time at 25 A, with average power dissipation of 29.125 W.

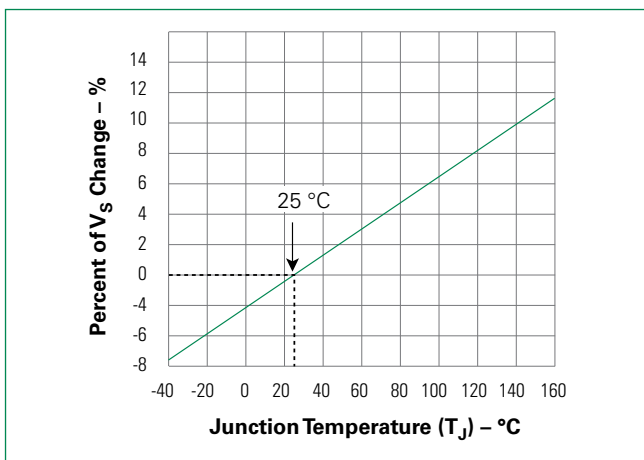
### V-I Characteristics



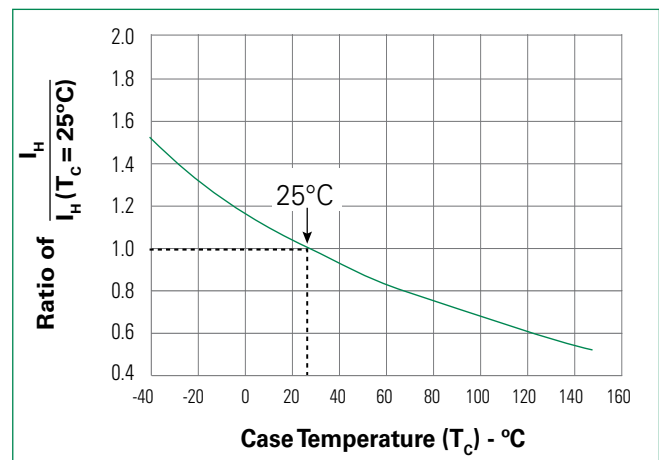
### t<sub>r</sub> x t<sub>d</sub> Pulse Waveform



### Normalized V<sub>S</sub> Change vs. Junction Temperature

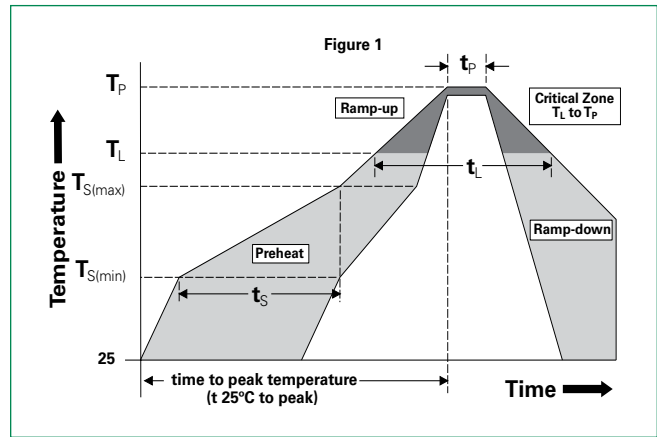


### Normalized DC Holding Current vs. Case Temperature



### Soldering Parameters

<b>Reflow Condition</b>		Pb-Free assembly
<b>Pre Heat</b>	- Temperature Min ( $T_{s(min)}$ )	+150°C
	- Temperature Max ( $T_{s(max)}$ )	+200°C
	- Time (Min to Max) ( $t_s$ )	60-180 secs.
<b>Average ramp up rate (Liquidus Temp (<math>T_L</math>) to peak)</b>		3°C/sec. Max.
<b><math>T_{s(max)}</math> to <math>T_L</math> - Ramp-up Rate</b>		3°C/sec. Max.
<b>Reflow</b>	- Temperature ( $T_L$ ) (Liquidus)	+217°C
	- Temperature ( $t_l$ )	60-150 secs.
<b>Peak Temp (<math>T_p</math>)</b>		+260(+0/-5)°C
<b>Time within 5°C of actual Peak Temp (<math>t_p</math>)</b>		30 secs. Max.
<b>Ramp-down Rate</b>		6°C/sec. Max.
<b>Time 25°C to Peak Temp (<math>T_p</math>)</b>		8 min. Max.
<b>Do not exceed</b>		+260°C



### Physical Specifications

<b>Lead Material</b>	Copper Alloy
<b>Terminal Finish</b>	100% Matte-Tin Plated
<b>Body Material</b>	UL recognized epoxy meeting flammability classification V-0

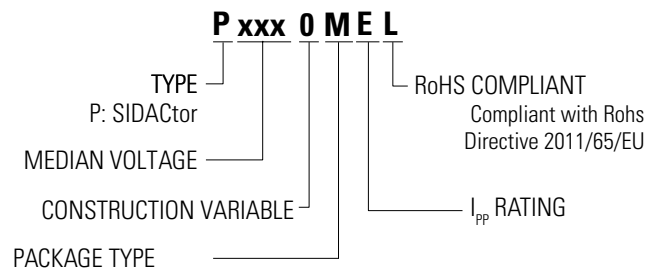
### Environmental Specifications

<b>High Temp Voltage Blocking</b>	80% Rated $V_{DRM}$ ( $V_{AC}$ Peak) +125°C or +150°C, 504 or 1008 hrs. MIL-STD-750 (Method 1040) JEDEC, JESD22-A-101
<b>Temp Cycling</b>	-65°C to +150°C, 15 min. dwell, 10 up to 100 cycles. MIL-STD-750 (Method 1051) EIA/JEDEC, JESD22-A104
<b>Biased Temp &amp; Humidity</b>	52 $V_{DC}$ (+85°C) 85%RH, 504 up to 1008 hrs. EIA/JEDEC, JESD22-A-101
<b>High Temp Storage</b>	+150°C 1008 hrs. MIL-STD-750 (Method 1031) JEDEC, JESD22-A-101
<b>Low Temp Storage</b>	-65°C, 1008 hrs.
<b>Thermal Shock</b>	0°C to +100°C, 5 min. dwell, 10 sec. transfer, 10 cycles. MIL-STD-750 (Method 1056) JEDEC, JESD22-A-106
<b>Autoclave (Pressure Cooker Test)</b>	+121°C, 100%RH, 2atm, 24 up to 168 hrs. EIA/JEDEC, JESD22-A-102
<b>Resistance to Solder Heat</b>	+260°C, 30 secs. MIL-STD-750 (Method 2031)
<b>Moisture Sensitivity Level</b>	85%RH, +85°C, 168 hrs., 3 reflow cycles (+260°C Peak). JEDEC-J-STD-020, Level 1

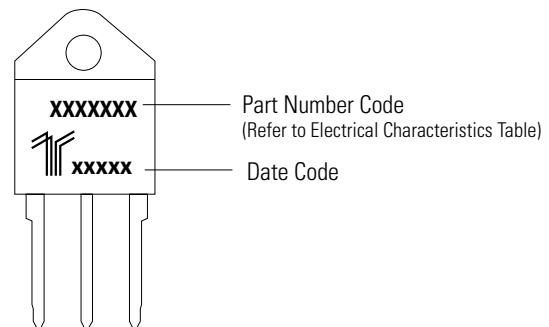
### Wave Solder (THD) Parameters and Lead-Free Requirements

Reflow Parameter	Lead-Free Requirement
Prehead (Depending on Flux Only)	
Temperature Min	150°C
Temperature Max	200°C
Time (Min to Max)	60 - 180 Seconds
Solder Pot Temperature	245 - 265°C (Max)
Solder Dwell Time	2 - 3.5 Seconds
Cooling	-6°C/Seconds (Max)

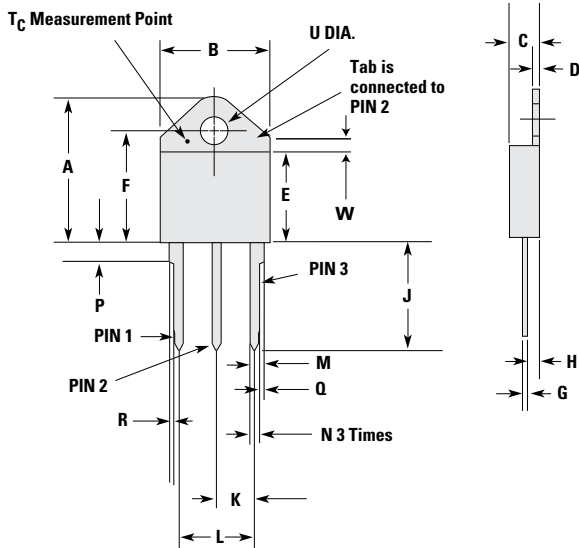
### Part Numbering



### Part Marking



**Dimensions — TO-218**



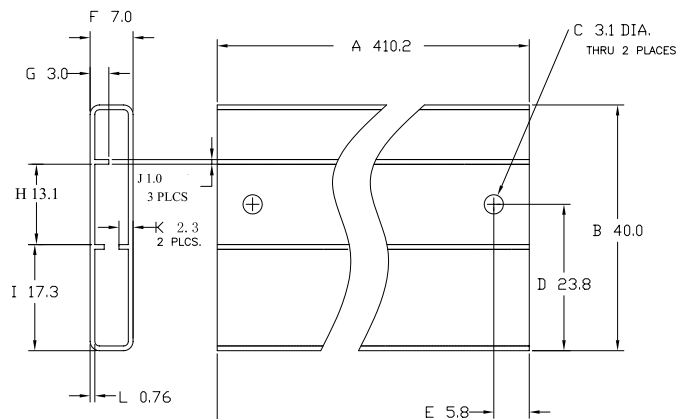
Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.810	0.835	20.57	21.21
B	0.610	0.630	15.49	16.00
C	0.178	0.188	4.52	4.78
D	0.055	0.070	1.40	1.78
E	0.487	0.497	12.37	12.62
F	0.635	0.655	16.13	16.64
G	0.022	0.029	0.56	0.74
H	0.075	0.095	1.91	2.41
J	0.575	0.625	14.61	15.88
K	0.211	0.219	5.36	5.56
L	0.422	0.437	10.72	11.10
M	0.058	0.068	1.47	1.73
N	0.045	0.055	1.14	1.40
P	0.095	0.115	2.41	2.92
R	0.008	0.016	0.20	0.41
U	0.161	0.165	4.1	4.2
W	0.085	0.095	2.17	2.42

- Notes:**
- Mold flash shall not exceed 0.13 mm per side.
  - Maximum torque to be applied to mounting tab is 8 in-lbs. (0.904 Nm).
  - Pin 3 has no connection.
  - Tab is non-isolated (connects to middle pin).

**Packing Options**

Package Type	Description	Packing Options Quantity	Added Suffix	Industry Standard
M	TO-218 (ME) Tube Pack	250(25 per tube/10 tubes per box)	N/A	N/A

**Tube Pack Specification — TO-218**



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